

P-Ch MOSFET

#### **General Description**

The WST3415 is the highest performance trench P-ch MOSFET with extreme high cell density, which provide excellent RDSON and gate charge for most of the small power switching and load switch applications.

The WST3415 meet the RoHS and Green Product requirement, with full function reliability approved.

#### Features

- Advanced high cell density Trench technology
- Super Low Gate Charge
- Excellent CdV/dt effect decline
- Green Device Available

#### **Product Summery**

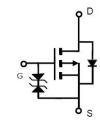
| BVDSS | RDSON | ID    |
|-------|-------|-------|
| -20V  | 44mΩ  | -5.5A |

#### Applications

- High Frequency Point-of-Load Synchronous Buck Converter for MB/NB/UMPC/VGA
- Networking DC-DC Power System
- ESD:3KV

#### SOT-23-3L Pin Configuration





### Absolute Maximum Ratings

| Symbol                              | Parameter   | Rating     | Units |  |
|-------------------------------------|---|------------|-------|--|
| V <sub>DS</sub>                     | Drain-Source Voltage  | -20        | V     |  |
| V <sub>GS</sub>                     | Gate-Source Voltage   | ±12        | V     |  |
| I <sub>D</sub> @T <sub>C</sub> =25℃ | Continuous Drain Current, V <sub>GS</sub> @ -4.5V <sup>1</sup> -5.5 |            | A     |  |
| I <sub>D</sub> @T <sub>C</sub> =70℃ | Continuous Drain Current, V <sub>GS</sub> @ -4.5V <sup>1</sup>      | -3.0       | A     |  |
| I <sub>DM</sub>                     | Pulsed Drain Current <sup>2</sup> -17                               |            | A     |  |
| P <sub>D</sub> @T <sub>A</sub> =25℃ | Total Power Dissipation <sup>3</sup>                                | 1.0        | W     |  |
| T <sub>STG</sub>                    | Storage Temperature Range -55 to 150                                |            | °C    |  |
| TJ                                  | Operating Junction Temperature Range                                | -55 to 150 | °C    |  |

#### Thermal Data

| Symbol           | Parameter  | Тур. | Max. | Unit |
|------------------|--|------|------|------|
| R <sub>θJA</sub> | Thermal Resistance Junction-Ambient <sup>1</sup> |      | 110  | °C/W |
| R <sub>eJC</sub> | Thermal Resistance Junction-Case <sup>1</sup>    |      | 70   | °C/W |



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#### Electrical Characteristics (T<sub>J</sub>=25<sup>-1</sup>C, unless otherwise noted)

| Symbol                               | Parameter                                      | Conditions   | Min. | Тур.   | Max.    | Unit  |
|--------------------------------------|--|--|------|--------|---------|-------|
| BV <sub>DSS</sub>                    | Drain-Source Breakdown Voltage                 | V <sub>GS</sub> =0V , I <sub>D</sub> =-250uA                         | -20  |        |         | V     |
| $\triangle BV_{DSS} / \triangle T_J$ | BV <sub>DSS</sub> Temperature Coefficient      | Reference to $25^{\circ}$ C , I <sub>D</sub> =-1mA                   |      | -0.016 |         | V/℃   |
|                                      |  | V <sub>GS</sub> =-4.5V , I <sub>D</sub> =-3A                         |      | 44     | 54      |       |
| R <sub>DS(ON)</sub>                  | Static Drain-Source On-Resistance <sup>2</sup> | V <sub>GS</sub> =-2.5V , I <sub>D</sub> =-2A                         |      | 53     | 62      | mΩ    |
|                                      |  | V <sub>GS</sub> =-1.8V , I <sub>D</sub> =-1A                         |      | 66     | 75      |       |
| V <sub>GS(th)</sub>                  | Gate Threshold Voltage                         |  | -0.3 | -0.75  | -1.0    | V     |
| V <sub>GS(th)</sub>                  | V <sub>GS(th)</sub> Temperature Coefficient    | $V_{GS}=V_{DS}$ , $I_D$ =-250uA                                      |      | 3.97   |         | mV/°C |
|                                      | Drain-Source Leakage Current                   | V <sub>DS</sub> =-16V , V <sub>GS</sub> =0V , T <sub>J</sub> =25℃    |      |        | 1       |       |
| I <sub>DSS</sub>                     |  | V <sub>DS</sub> =-16V , V <sub>GS</sub> =0V , T <sub>J</sub> =55℃    |      |        | 5       | uA    |
| I <sub>GSS</sub>                     | Gate-Source Leakage Current                    | $V_{GS}=\pm8V$ , $V_{DS}=0V$   |      |        | ±100    | nA    |
| gfs                                  | Forward Transconductance                       | V <sub>DS</sub> =-5V , I <sub>D</sub> =-3A                           |      | 14     |         | S     |
| Qg                                   | Total Gate Charge (-4.5V)                      |  |      | 6.2    | 9       |       |
| Q <sub>gs</sub>                      | Gate-Source Charge                             | V <sub>DS</sub> =-15V , V <sub>GS</sub> =-4.5V , I <sub>D</sub> =-3A |      | 2.2    | 2.5     | nC    |
| Q <sub>gd</sub>                      | Gate-Drain Charge                              |  |      | 1.8    | 2.6     |       |
| T <sub>d(on)</sub>                   | Turn-On Delay Time                             |  |      | 2.7    | 5.5     |       |
| Tr                                   | Rise Time                                      | V <sub>DD</sub> =-10V , V <sub>GS</sub> =-4.5V ,                     |      | 8.4    | 15      |       |
| T <sub>d(off)</sub>                  | Turn-Off Delay Time                            | R <sub>G</sub> =3.3Ω, I <sub>D</sub> =-3A                            |      | 38     | 8 78 ns |       |
| T <sub>f</sub>                       | Fall Time                                      |  |      | 6      | 12      | 1     |
| C <sub>iss</sub>                     | Input Capacitance                              |  |      | 575    |         |       |
| C <sub>oss</sub>                     | Output Capacitance                             | V <sub>DS</sub> =-15V , V <sub>GS</sub> =0V , f=1MHz                 |      | 98     |         | pF    |
| C <sub>rss</sub>                     | Reverse Transfer Capacitance                   |  |      | 75     |         |       |

#### **Diode Characteristics**

| Symbol          | Parameter                                | Conditions  | Min. | Тур. | Max. | Unit |
|-----------------|--|---|------|------|------|------|
| I <sub>S</sub>  | Continuous Source Current <sup>1,4</sup> |   |      |      | -1   | А    |
| I <sub>SM</sub> | Pulsed Source Current <sup>2,4</sup>     | $V_G = V_D = 0V$ , Force Current                                |      |      | -17  | А    |
| V <sub>SD</sub> | Diode Forward Voltage <sup>2</sup>       | V <sub>GS</sub> =0V , I <sub>S</sub> =-1A , T <sub>J</sub> =25℃ |      |      | -1   | V    |
| t <sub>rr</sub> | Reverse Recovery Time                    |   |      | 28   |      | nS   |
| Q <sub>rr</sub> | Reverse Recovery Charge                  | IF=-3A , dl/dt=100A/µs , T <sub>J</sub> =25 $^\circ \mathbb{C}$ |      | 25   |      | nC   |

Note :

1. The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 2OZ copper,t<10sec.

2. The data tested by suffice insuffice on a matrix for the second seco

4.The data is theoretically the same as  $I_D$  and  $I_{DM}$ , in real applications , should be limited by total power dissipation.



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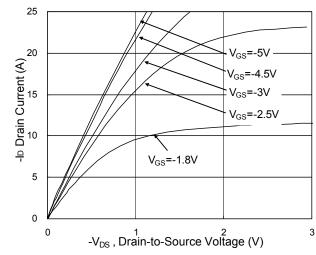


Fig.1 Typical Output Characteristics

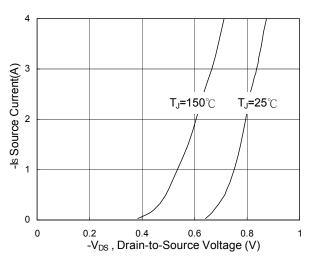


Fig.3 Forward Characteristics of Reverse

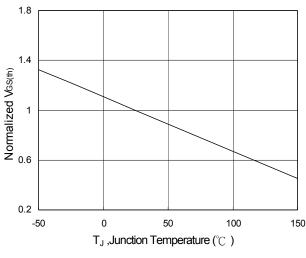


Fig.5 Normalized  $V_{GS(th)}$  vs.  $T_J$ 

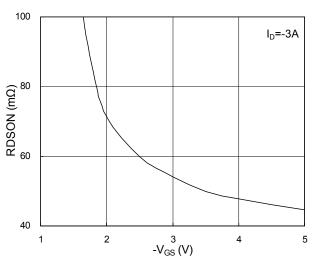


Fig.2 On-Resistance vs. G-S Voltage

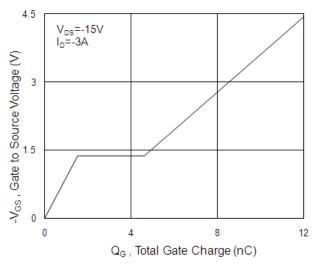


Fig.4 Gate-Charge Characteristics

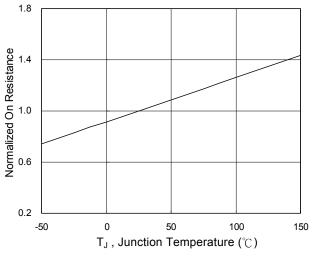


Fig.6 Normalized  $R_{\text{DSON}}$  vs.  $T_{\text{J}}$ 



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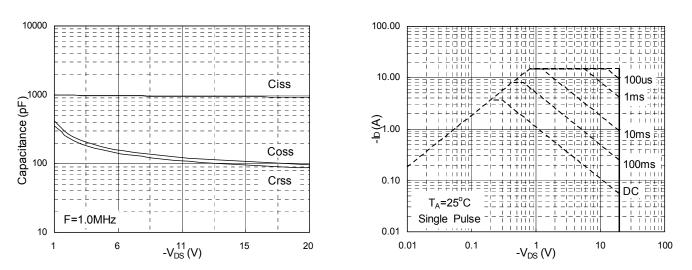




Fig.8 Safe Operating Area

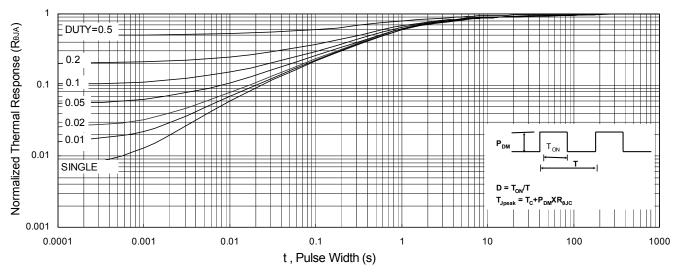
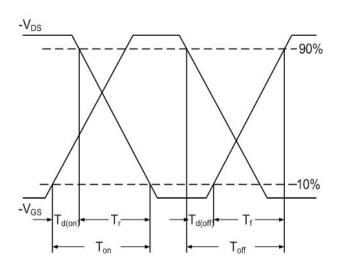
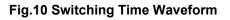
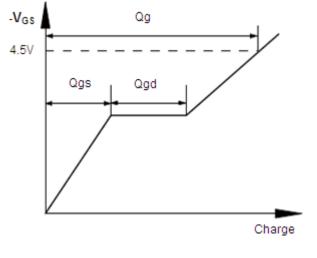


Fig.9 Normalized Maximum Transient Thermal Impedance











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